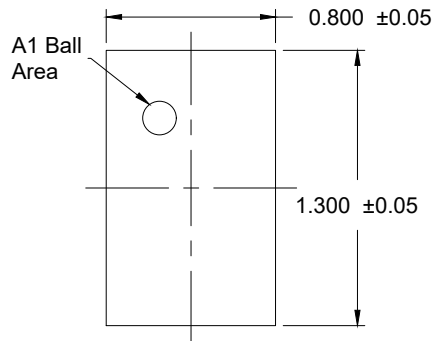
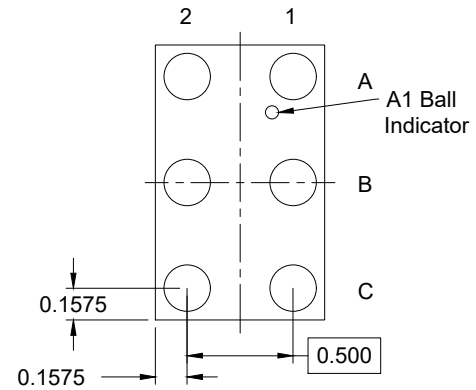
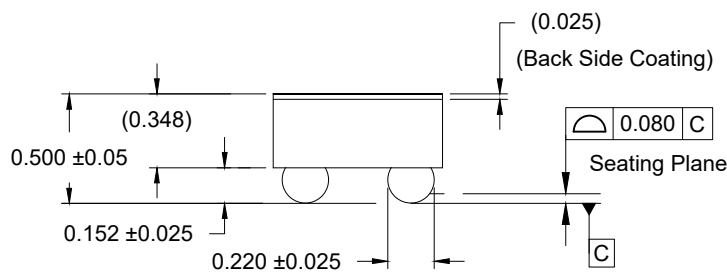




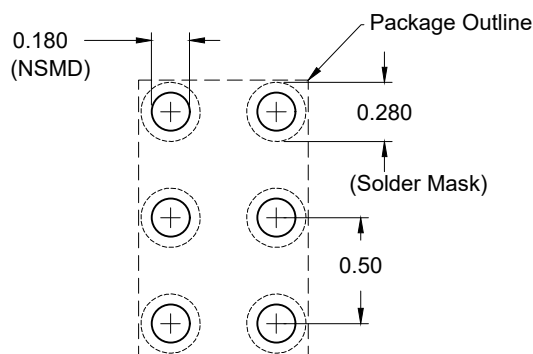
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN  
(PCB Top View, NSMD Design)

## NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use  $\pm 0.05$  mm for the non-toleranced dimensions.
4. Numbers in ( ) are for references only.
5. Pre-reflow solder ball diameter is  $\varnothing 0.200$  mm.
6. UBM diameter is  $\varnothing 0.200$  mm.